

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A hybrid circuit comprising  
a substrate;  
interconnects on said substrate;  
a first IC die with electrical functionality, said first IC die being attached to said  
substrate and having input and output signal leads connected to the said interconnects via  
bonding mechanisms; and  
programmable logic on said IC die, wherein  
said programmable logic is operative to intercept selected ones of  
communication signals between said IC die and said ~~substrate~~ substrate, wherein  
said programmable logic is operative in response to external control  
signals applied to said programmable logic, and  
said control signals are operative to modify electrical functionality and  
connectivity of inputs and outputs connected to said programmable logic.
2. (Original) The hybrid circuit according to claim 1 wherein said substrate  
includes active devices.
3. (Original) The hybrid circuit according to claim 2 wherein said substrate  
includes programmable logic.
4. (Original) The hybrid circuit according to claim 3 wherein said  
programmable logic is disposed to intercept said interconnects.
5. (Canceled).
6. (Original) The hybrid circuit according to claim 1 further including  
redundant inputs and outputs on the same IC die.

7. (Original) The hybrid circuit according to claim 1 wherein said IC die contains at least two electrical functional units; and wherein  
said programmable logic is operative to select one of the two electrical functional units for connection to external outputs of the die under the control of control signals.

8. (Original) The hybrid circuit according to claim 7 wherein said two functional electric functional units are substantially identical in functionality.

9. (Original) The hybrid circuit according to claim 8 wherein said substrate includes active circuitry.

10. (Original) The hybrid circuit according to claim 7 wherein power control is provided which is operative to switch off power supply to a single one of said electrical functional units.

11. (Original) The hybrid circuit according to claim 7 wherein said substrate further includes active circuitry.

12. (Original) The hybrid circuit according to claim 7 wherein said control circuit is operative to selectively cut off clock input to at least one said electrical functional unit.

13. (Currently Amended) A hybrid circuit comprising:  
a substrate;  
interconnects on said substrate;  
an IC die on said substrate, said IC die having at least two functional units and control logic connected to output terminals of said functional units and connected to input/output terminals of said IC die, wherein said control logic is responsive to external control signals applied to said control logic and said control signals are operative to modify electrical functionality and connectivity of inputs and outputs connected to said control logic; and  
said control logic being operative to connect outputs of one selected functional unit to selected input/output terminals of the IC die.

14. (Original) The hybrid circuit according to claim 13 wherein said two functional units are of identical functionality.

15-18. (Canceled).

19. (Original) A method for routing signals within a hybrid circuit on a substrate, said substrate having interconnects on said substrate, a first IC die with electrical functionality, said first IC die being attached to said substrate and having input and output signal leads connected to the said interconnects via bonding mechanisms, a second IC die with electrical functionality, said second IC die being attached to said substrate and having input and output signal leads connected to the said interconnects via bonding mechanisms, and programmable logic on said IC die, the method comprising:

intercepting via said interconnects selected communication signals between said first IC die and said substrate; and

switching signal lines via said programmable logic between first IC die and said second IC die.